## Light Emitting Diodes

# LN322GPH

# Round-Top View Type

 $\varphi 2.0\ mm$  Series

## Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	90	mW	
Forward current	I <sub>F</sub>	30	mA	
Pulse forward current *	I <sub>FP</sub>	150	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-30 to +100	°C	

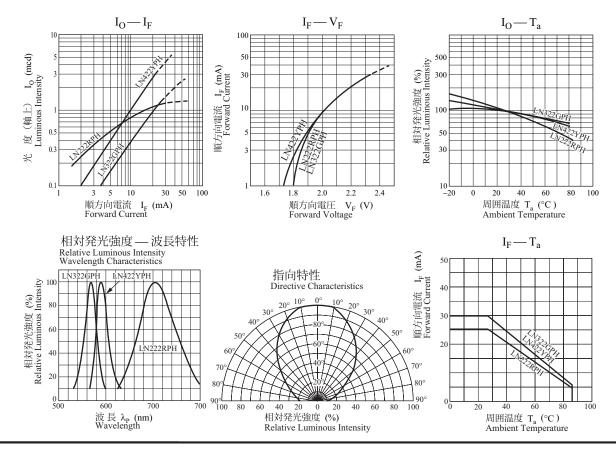
Lighting Color / Lens Color

• Green / Green Diffused

Note) \*: The condition of  $I_{\rm FP}$  is duty 10%, Pulse width 1 msec.

#### Electro-Optical Characteristics $T_a = 25^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>		0.4	1.0		mcd
Forward current	I <sub>F</sub>			20		mA
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 20  {\rm mA}$		2.2	2.8	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 20  {\rm mA}$		565		nm
Spectral half band width	Δλ	$I_{\rm F} = 20  {\rm mA}$		30		nm
Reverse current	I <sub>R</sub>	$V_R = 4 V$			10	μΑ

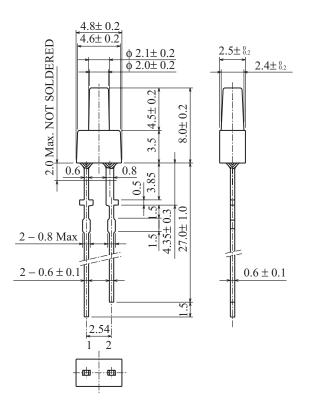


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# **Panasonic**

Package (Unit: mm)



• Pin name

1: Anode

2: Cathode

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